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09/105006



06/26/98

Case Docket No. 980766 U.S. DEPARTMENT OF COMMERCE
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To the Assistant Commissioner for Patents.
Please record the attached original documents or copy thereof.

1. Name of conveying party:

MRD
6-26-98

Tadayuki SHIMURA

Additional name(s) of conveying party(ies) attached? NO

2. Name and address of receiving party:

Name: FUJITSU LIMITED

Street Address:

1-1, Kamikodanaka 4-chome, Nakahara-ku,
Kawasaki-shi, Kanagawa 211-8588, Japan

Additional name(s) & address(es) attached? NO

3. Nature of conveyance: **Assignment**

Execution Date: May 26, 1998

4. Title:

SEMICONDUCTOR DEVICE HAVING A FLIP-CHIP STRUCTURE

5. Application number(s) or patent number(s): 09/105,006

If this document is being filed together with a new application, the execution date of the application is: May 26, 1998

00000047 09105006

40.00 DP

Additional numbers attached? NO

07/06/1998 TDADE1
02 FC:581

PATENT

REEL: 9295 FRAME: 0416

6. Name and address of party to whom correspondence concerning document should be mailed:

Name: Armstrong, Westerman, Hattori,
McLeland & Naughton
Suite 1000
1725 K Street, N.W.
Washington, D.C. 20006

7. Total number of applications and patents involved: 1

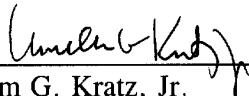
8. Total fee (37 CFR 3.41). \$ **40.00**

XX Check enclosed

9. Deposit Account No.: **01-2340**

10. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.



William G. Kratz, Jr.
Reg. No.: 22,631

Date June 26, 1998

Total number of pages including cover sheet: 3

WGK/tmb

U.S. ASSIGNMENT

IN CONSIDERATION of the sum of One Dollar (\$1.00), and of other good and valuable consideration paid to the undersigned inventor(s) (hereinafter ASSIGNOR) by

(Insert ASSIGNEE's
Name(s) Address(es))

FUJITSU LIMITED,
1-1, Kamikodanaka 4-chome, Nakahara-ku,
Kawasaki-shi, Kanagawa, 211-8588 Japan

(hereinafter ASSIGNEE), the receipt of which is hereby acknowledged, the undersigned ASSIGNOR hereby sells, assigns and transfers to ASSIGNEE the entire and exclusive right, title and interest to the invention entitled

(Title of Invention)

SEMICONDUCTOR DEVICE HAVING A FLIP-CHIP STRUCTURE

(*If the assignment is
being filed after the filing
of the application, this
section must be
completed)

for which application for Letters Patent of the United States was executed on even date herewith unless otherwise indicated below:

*filed on _____, Serial No. _____.
(Armstrong, Westerman, Hattori, McLeland & Naughton is hereby authorized to insert the series code, serial number and/or filing date hereon, when known)

and all Letters Patent of the United States to be obtained therefor on said application or any continuation, divisional, substitute, reissue or reexamination thereof for the full term or terms for which the same may be granted.

The ASSIGNOR agrees to execute all papers necessary in connection with the application and any continuation, divisional, reissue or reexamination applications thereof and also to execute separate assignments in connection with such applications as the ASSIGNEE may deem necessary or expedient.

The ASSIGNOR agrees to execute all papers necessary in connection with any interference, litigation, or other legal proceeding which may be declared concerning this application or any continuation, divisional, reissue or reexamination thereof or Letters Patent or reissue patent issued thereon and to cooperate with the ASSIGNEE in every way possible in obtaining and producing evidence and proceeding with such interference, litigation, or other legal proceeding.

IN WITNESS WHEREOF, the undersigned inventor(s) has (have) affixed his/her/their signature(s).

(Signatures)

<u>Tadayuki Shimura</u> (SIGNATURE)	<u>Tadayuki Shimura</u> (TYPE NAME)	<u>May 26, 1998</u> (DATE)
_____ (SIGNATURE)	_____ (TYPE NAME)	_____ (DATE)
_____ (SIGNATURE)	_____ (TYPE NAME)	_____ (DATE)
_____ (SIGNATURE)	_____ (TYPE NAME)	_____ (DATE)
_____ (SIGNATURE)	_____ (TYPE NAME)	_____ (DATE)
_____ (SIGNATURE)	_____ (TYPE NAME)	_____ (DATE)